



PRODUCT OVERVIEW

Stencil, Screen & Misprint Cleaning

For the removal of solder pastes, SMT adhesives and flux residues from stencils, screens and misprinted boards.

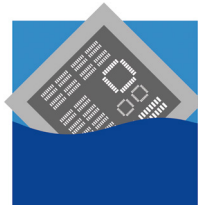
Our Technical Centers in Europe, America and Asia are at your disposal to help you determine the most suitable stencil cleaner for your application:

- ▶ World's largest selection of spray-in-air, ultrasonic or spray-under-immersion machines - inline or batch systems - from leading manufacturers.
- ▶ Individual and uncommitted advice by local ZESTRON process engineers.
- ▶ Inspection of cleaning results according to international standards within one day.

To conduct free-of-charge cleaning trials, please contact us at: techsupport@zestron.com.

		Contamination	Fluxes (from leaded and lead-free solder pastes)	Solder Pastes (leaded and lead-free)	SMT Adhesives	Thick Film Pastes / Photovoltaics
Process						
Water-based	 Ultrasonic Equipment		VIGON® SC 200			
			VIGON® SC 202			
	 Spray-in-Air Equipment		VIGON® SC 210			
			VIGON® SC			
			HYDRON® SC 300			
 Stencil Printer Underside Wipe			VIGON® SC 200			
			VIGON® UC 160			
	 Manual Stencil Cleaning		VIGON® SC 200			
Solvent-based	 Spray-in-Air Equipment		ZESTRON® SD 100			
			ZESTRON® SD 301			
	 Spray-in-Air Equipment		ZESTRON® SW			
		 Manual Stencil Cleaning		ZESTRON® SD 301		

For detailed product information, please see reverse or visit us at www.zestron.com.



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Stencil, Screen & Misprint Cleaning

The following cleaning media are recommended for the removal of solder pastes, SMT adhesives or flux residues from stencils, screens and misprinted boards.



Water-based; Spray-In-Air or Ultrasonic Equipment

Cleaners based on MPC®-Technology

VIGON® SC 200

- ▶ Removes solder paste, SMT adhesive and some fluxes
- ▶ Ambient cleaning temperature (ideal for thermally sensitive SMT adhesives)
- ▶ Extremely long bath life

VIGON® SC 202

- ▶ Removes solder paste, SMT adhesive and most fluxes
- ▶ Ideal for the cleaning of populated and soldered misprinted assemblies
- ▶ Improved cleaning performance for flux removal

VIGON® SC 210

- ▶ Removes solder paste, SMT adhesive and some fluxes
- ▶ Good cleaning performance, even down to 18° C
- ▶ For equipment with high consumption per cleaning cycle

VIGON® SC

- ▶ Removes solder paste and SMT adhesive
- ▶ Dries twice as fast as water
- ▶ Rinsing with VIGON® SC or water is possible
- ▶ Cleaning temperature: 40-50° C (104-125° F)

Cleaners based on HYDRON®-Technology

HYDRON® SC 300

- ▶ Removes solder paste, SMT adhesive and some fluxes
- ▶ Does not leave any adhesive pigment residues
- ▶ Dries residue-free



Solvent-based; Spray-In-Air Equipment

ZESTRON® SD 100

- ▶ Effectively removes solder paste
- ▶ High flash point (can be used at ambient temperature without external explosion protection)
- ▶ Faster drying than water-based cleaning agents
- ▶ High bath loading capacity results in an extended bath life
- ▶ Ideal as an IPA replacement in stencil cleaning equipment

ZESTRON® SD 301

- ▶ Faster drying than water-based cleaning agents
- ▶ Odor optimized formulation
- ▶ Suitable for the removal of aluminum- and silverconductive pastes
- ▶ Safe work environment due to mild formulation

For Technical Information sheets: www.zestron.com



Stencil Printer Underside Wipe Systems

VIGON® SC 200

- ▶ Water-based medium without flash point
- ▶ Mild odor

VIGON® UC 160

- ▶ Especially developed for SMT printers
- ▶ Water-based medium, low consumption, no flash point

ZESTRON® SW

- ▶ Solvent-based, fast drying
- ▶ A flash point of 67° C (153° F) guarantees safe use in stencil printing equipment

▶ All cleaners approved by leading printer manufacturers, suitable for nano-coated stencils



Manual Cleaning

VIGON® SC 200 and ZESTRON® SD 301

- ▶ Both media can also be used for manual stencil cleaning. For this application both products are available in special 1L bottles.

MPC® Technology:

- ▶ No flash point
- ▶ High bath loading capacity
- ▶ Unrivalled bath life
- ▶ Low maintenance costs
- ▶ Closed loop process possible
- ▶ Leaves no residues on surfaces and/or in the cleaning equipment